



METCLAD

INTERNATIONAL CORP

FAMILY
MYIM

MYIM is specifically designed to achieve **Passive Intermodulation Performance**. It is our lowest loss, high performance, metal clad laminate family specifically designed to achieve **low Passive Intermodulation Performance in RF and microwave applications**. They are manufactured from woven glass reinforced PTFE. The percentage of PTFE is very tightly controlled to accurately maintain the specified value of dielectric constant, loss and thickness. Metclad **MYIM** laminates are tested in accordance with IPC-TM-650 and meet the requirements of IPC-L-125A. Metclad **MYIM** laminates are the subject of a patent application.

DK	2.17	2.20	2.33
DF	.0008	.0009	.0011

Typical Parameter	Test Method	Typical Value
Dielectric Constant at 10GHz	IPC-TM-650, 2.5.5.5	see above
Tolerance		± 0.02
Dissipation Factor at 10GHz	IPC-TM-650, 2.5.5.5	see above
Intermodulation Performance		-155 dBc
Dielectric Breakdown	IPC-TM-650, 2.5.6	50kV
Volume Resistivity	IPC-TM-650, 2.5.17.1	10 ⁹ MΩ/cm
Surface Resistivity	IPC-TM-650, 2.5.17.1	10 ⁷ MΩ
Arc Resisance	ASTM D-495	180 sec
Flexural Strength Lengthwise	IPC-TM-650, 2.4.4	12,000 lbs/in
Flexural Strength Crosswise	IPC-TM-650, 2.4.4	10,000 lbs/in
Copper Peel Strength (18, 35 and 70µm copper) After Thermal Shock (30s at 260°C)	IPC-TM-650, 2.4.8	13 lbs/in 12 lbs/in
Moisture Absorption	IPC-TM-650, 2.6.2.1	0.02%
Specific Gravity	ASTM D-792, A	2.23 g/cm ³
Thermal Conductivity	ASTM E-1225	0.272 W/m/K
Coefficient of Thermal Expansion (CTE) X Y Z	IPC-TM-650, 2.4.41	25 ppm/°C 35 ppm/°C 260 ppm/°C
Flamibility	IPC-TM-650, 2.3.10	V-0

The above represents typical values. As a policy of continuous improvement, Metclad International Corp. reserves the right to change specifications at any time.